

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YI-CHAO MAO	07/11/2017
CHIN-CHUAN CHANG	07/11/2017
JING-CHENG LIN	07/11/2017
WEN-HUA CHANG	07/11/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	30078
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15652244
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>NAME OF SUBMITTER:</b>	BELINDA LEE
<b>SIGNATURE:</b>	/Belinda Lee/
<b>DATE SIGNED:</b>	08/23/2017
<b>Total Attachments: 3</b>	
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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

☐ Declaration Submitted With Initial Filing

OR

☒ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**GRINDING ELEMENT, GRINDING WHEEL AND MANUFACTURING  
METHOD OF SEMICONDUCTOR PACKAGE USING THE SAME**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

☐ The attached application,

OR

☒ United States Application Number or PCT International application number 15/652,244  
Filed on July 18, 2017.

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

P20161587US00  
68899-US-PA

**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. Taiwan Semiconductor Manufacturing Co., Ltd.  
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,  
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P20161587US00  
68899-US-PA

**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Yi-Chao Mao Date: 2017 / 7 / 11

Legal Name of Sole or First Inventor: Yi-Chao Mao

Residence: Taoyuan County, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chin-Chuan Chang Date: 2017. 7. 11

Legal Name of Additional Joint Inventor, if any: Chin-Chuan Chang

Residence: Hsinchu County, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Jing-Cheng Lin Date: 2017. 7. 11

Legal Name of Additional Joint Inventor, if any: Jing-Cheng Lin

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Wen-Hua Chang Date: 2017 / 7 / 11

Legal Name of Additional Joint Inventor, if any: Wen-Hua Chang

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